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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	83
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b510f2048gq100-ar

5. Pin Definitions	115
5.1 EFM32GG11B8xx in BGA192 Device Pinout	115
5.2 EFM32GG11B8xx in BGA152 Device Pinout	119
5.3 EFM32GG11B8xx in BGA120 Device Pinout	123
5.4 EFM32GG11B5xx in BGA120 Device Pinout	126
5.5 EFM32GG11B4xx in BGA120 Device Pinout	129
5.6 EFM32GG11B4xx in BGA112 Device Pinout	132
5.7 EFM32GG11B3xx in BGA112 Device Pinout	135
5.8 EFM32GG11B8xx in QFP100 Device Pinout	138
5.9 EFM32GG11B5xx in QFP100 Device Pinout	141
5.10 EFM32GG11B4xx in QFP100 Device Pinout	144
5.11 EFM32GG11B3xx in QFP100 Device Pinout	147
5.12 EFM32GG11B8xx in QFP64 Device Pinout	150
5.13 EFM32GG11B5xx in QFP64 Device Pinout	152
5.14 EFM32GG11B4xx in QFP64 Device Pinout	154
5.15 EFM32GG11B1xx in QFP64 Device Pinout	156
5.16 EFM32GG11B8xx in QFN64 Device Pinout	158
5.17 EFM32GG11B5xx in QFN64 Device Pinout	160
5.18 EFM32GG11B4xx in QFN64 Device Pinout	162
5.19 EFM32GG11B1xx in QFN64 Device Pinout	164
5.20 GPIO Functionality Table	166
5.21 Alternate Functionality Overview	178
5.22 Analog Port (APORT) Client Maps	211
6. BGA192 Package Specifications	224
6.1 BGA192 Package Dimensions	224
6.2 BGA192 PCB Land Pattern	226
6.3 BGA192 Package Marking	228
7. BGA152 Package Specifications	229
7.1 BGA152 Package Dimensions	229
7.2 BGA152 PCB Land Pattern	231
7.3 BGA152 Package Marking	233
8. BGA120 Package Specifications	234
8.1 BGA120 Package Dimensions	234
8.2 BGA120 PCB Land Pattern	236
8.3 BGA120 Package Marking	238
9. BGA112 Package Specifications	239
9.1 BGA112 Package Dimensions	239

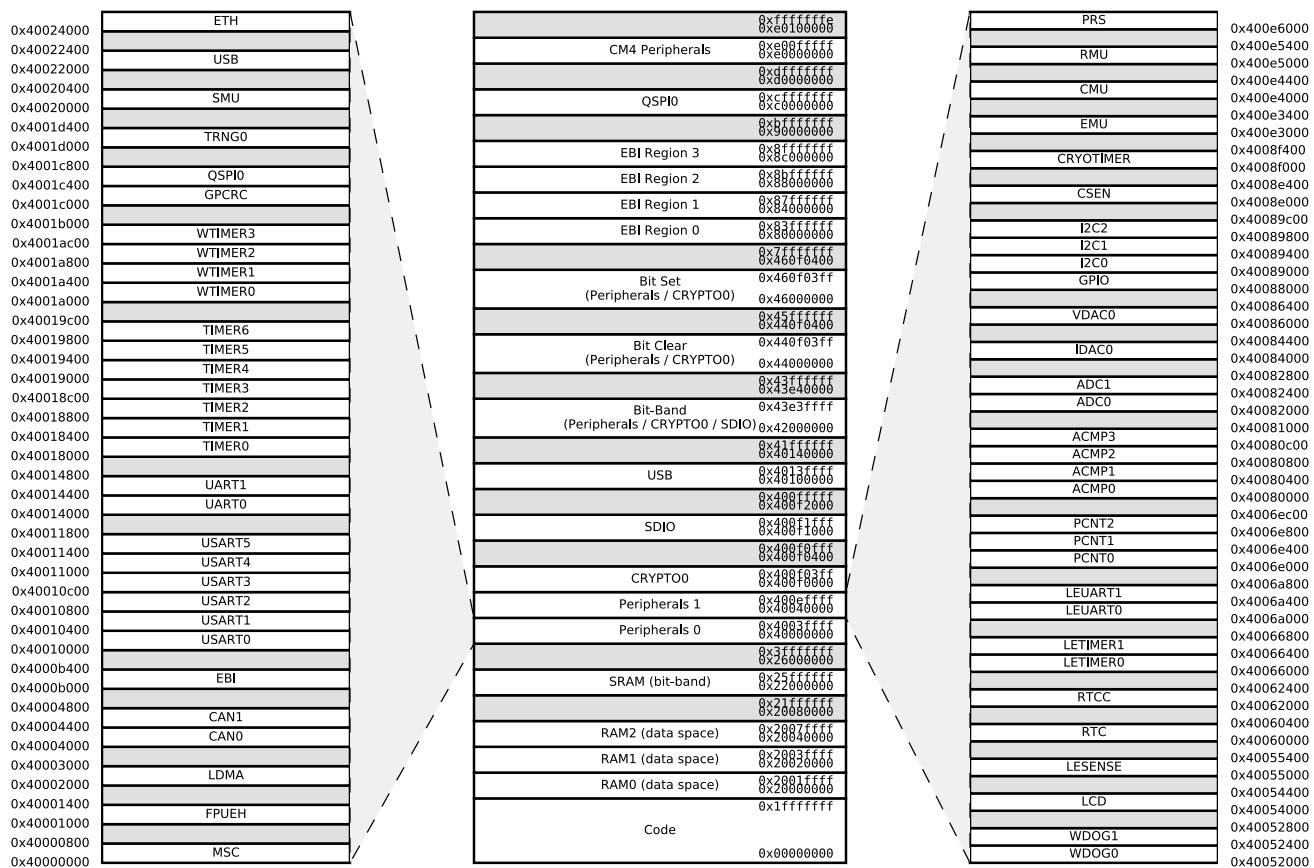


Figure 3.3. EFM32GG11 Memory Map — Peripherals

4.1.2.1 General Operating Conditions

Table 4.2. General Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating ambient temperature range ⁶	T _A	-G temperature grade	-40	25	85	°C
		-I temperature grade	-40	25	125	°C
AVDD supply voltage ²	V _{AVDD}		1.8	3.3	3.8	V
VREGVDD operating supply voltage ^{2 1}	V _{VREGVDD}	DCDC in regulation	2.4	3.3	3.8	V
		DCDC in bypass, 50mA load	1.8	3.3	3.8	V
		DCDC not in use. DVDD externally shorted to VREGVDD	1.8	3.3	3.8	V
VREGVDD current	I _{VREGVDD}	DCDC in bypass, T ≤ 85 °C	—	—	200	mA
		DCDC in bypass, T > 85 °C	—	—	100	mA
DVDD operating supply voltage	V _{DVDD}		1.62	—	V _{VREGVDD}	V
IOVDD operating supply voltage	V _{IOVDD}	All IOVDD pins ⁵	1.62	—	V _{VREGVDD}	V
DECOUPLE output capacitor ^{3 4}	C _{DECOUPLE}		0.75	1.0	2.75	μF
HFCORECLK frequency	f _{CORE}	VSCALE2, MODE = WS3	—	—	72	MHz
		VSCALE2, MODE = WS2	—	—	54	MHz
		VSCALE2, MODE = WS1	—	—	36	MHz
		VSCALE2, MODE = WS0	—	—	18	MHz
		VSCALE0, MODE = WS2	—	—	20	MHz
		VSCALE0, MODE = WS1	—	—	14	MHz
		VSCALE0, MODE = WS0	—	—	7	MHz
HFCLK frequency	f _{HFCLK}	VSCALE2	—	—	72	MHz
		VSCALE0	—	—	20	MHz
HFSRCCLK frequency	f _{HFSRCCLK}	VSCALE2	—	—	72	MHz
		VSCALE0	—	—	20	MHz
HFBUSCLK frequency	f _{HFBUSCLK}	VSCALE2	—	—	50	MHz
		VSCALE0	—	—	20	MHz
HFPERCLK frequency	f _{HFPERCLK}	VSCALE2	—	—	50	MHz
		VSCALE0	—	—	20	MHz
HFPERBCLK frequency	f _{HFPERBCLK}	VSCALE2	—	—	72	MHz
		VSCALE0	—	—	20	MHz
HFPERCCLK frequency	f _{HFPERCCLK}	VSCALE2	—	—	50	MHz
		VSCALE0	—	—	20	MHz

4.1.7.3 Current Consumption 1.8 V without DC-DC Converter

Unless otherwise indicated, typical conditions are: VREGVDD = AVDD = DVDD = 1.8 V. T = 25 °C. DCDC is off. Minimum and maximum values in this table represent the worst conditions across supply voltage and process variation at T = 25 °C.

Table 4.9. Current Consumption 1.8 V without DC-DC Converter

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 mode with all peripherals disabled	I _{ACTIVE}	72 MHz HFRCO, CPU running Prime from flash	—	120	—	µA/MHz
		72 MHz HFRCO, CPU running while loop from flash	—	120	—	µA/MHz
		72 MHz HFRCO, CPU running CoreMark loop from flash	—	140	—	µA/MHz
		50 MHz crystal, CPU running while loop from flash	—	122	—	µA/MHz
		48 MHz HFRCO, CPU running while loop from flash	—	122	—	µA/MHz
		32 MHz HFRCO, CPU running while loop from flash	—	124	—	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	126	—	µA/MHz
		16 MHz HFRCO, CPU running while loop from flash	—	131	—	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	315	—	µA/MHz
Current consumption in EM0 mode with all peripherals disabled and voltage scaling enabled	I _{ACTIVE_VS}	19 MHz HFRCO, CPU running while loop from flash	—	107	—	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	259	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled	I _{EM1}	72 MHz HFRCO	—	57	—	µA/MHz
		50 MHz crystal	—	59	—	µA/MHz
		48 MHz HFRCO	—	59	—	µA/MHz
		32 MHz HFRCO	—	61	—	µA/MHz
		26 MHz HFRCO	—	63	—	µA/MHz
		16 MHz HFRCO	—	68	—	µA/MHz
		1 MHz HFRCO	—	252	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled and voltage scaling enabled	I _{EM1_VS}	19 MHz HFRCO	—	55	—	µA/MHz
		1 MHz HFRCO	—	207	—	µA/MHz
Current consumption in EM2 mode, with voltage scaling enabled	I _{EM2_VS}	Full 512 kB RAM retention and RTCC running from LFXO	—	3.7	—	µA
		Full 512 kB RAM retention and RTCC running from LFRCO	—	4.0	—	µA
		16 kB (1 bank) RAM retention and RTCC running from LFRCO ²	—	2.5	—	µA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Slew rate ⁵	SR	DRIVESTRENGTH = 3, INCBW=1 ³	—	4.7	—	V/μs
		DRIVESTRENGTH = 3, INCBW=0	—	1.5	—	V/μs
		DRIVESTRENGTH = 2, INCBW=1 ³	—	1.27	—	V/μs
		DRIVESTRENGTH = 2, INCBW=0	—	0.42	—	V/μs
		DRIVESTRENGTH = 1, INCBW=1 ³	—	0.17	—	V/μs
		DRIVESTRENGTH = 1, INCBW=0	—	0.058	—	V/μs
		DRIVESTRENGTH = 0, INCBW=1 ³	—	0.044	—	V/μs
		DRIVESTRENGTH = 0, INCBW=0	—	0.015	—	V/μs
Startup time ⁶	T _{START}	DRIVESTRENGTH = 2	—	—	12	μs
Input offset voltage	V _{Osi}	DRIVESTRENGTH = 2 or 3, T = 25 °C	TBD	—	TBD	mV
		DRIVESTRENGTH = 1 or 0, T = 25 °C	TBD	—	TBD	mV
		DRIVESTRENGTH = 2 or 3, across operating temperature range	TBD	—	TBD	mV
		DRIVESTRENGTH = 1 or 0, across operating temperature range	TBD	—	TBD	mV
DC power supply rejection ratio ⁹	PSRR _{DC}	Input referred	—	70	—	dB
DC common-mode rejection ratio ⁹	CMRR _{DC}	Input referred	—	70	—	dB
Total harmonic distortion	THD _{OPA}	DRIVESTRENGTH = 2, 3x Gain connection, 1 kHz, V _{OUT} = 0.1 V to V _{OPA} - 0.1 V	—	90	—	dB
		DRIVESTRENGTH = 0, 3x Gain connection, 0.1 kHz, V _{OUT} = 0.1 V to V _{OPA} - 0.1 V	—	90	—	dB

4.1.21 Pulse Counter (PCNT)**Table 4.29. Pulse Counter (PCNT)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input frequency	F_{IN}	Asynchronous Single and Quadrature Modes	—	—	20	MHz
		Sampled Modes with Debounce filter set to 0.	—	—	8	kHz

4.1.22 Analog Port (APORT)**Table 4.30. Analog Port (APORT)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply current ^{2 1}	I_{APORT}	Operation in EM0/EM1	—	7	—	μA
		Operation in EM2/EM3	—	915	—	nA

Note:

1. Specified current is for continuous APORt operation. In applications where the APORt is not requested continuously (e.g. periodic ACMP requests from LESENSE in EM2), the average current requirements can be estimated by multiplying the duty cycle of the requests by the specified continuous current number.
2. Supply current increase that occurs when an analog peripheral requests access to APORt. This current is not included in reported module currents. Additional peripherals requesting access to APORt do not incur further current.

4.1.23.3 I2C Fast-mode Plus (Fm+)¹Table 4.33. I2C Fast-mode Plus (Fm+)¹

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency ²	f_{SCL}		0	—	1000	kHz
SCL clock low time	t_{LOW}		0.5	—	—	μs
SCL clock high time	t_{HIGH}		0.26	—	—	μs
SDA set-up time	t_{SU_DAT}		50	—	—	ns
SDA hold time	t_{HD_DAT}		100	—	—	ns
Repeated START condition set-up time	t_{SU_STA}		0.26	—	—	μs
(Repeated) START condition hold time	t_{HD_STA}		0.26	—	—	μs
STOP condition set-up time	t_{SU_STO}		0.26	—	—	μs
Bus free time between a STOP and START condition	t_{BUF}		0.5	—	—	μs

Note:

- 1. For CLHR set to 0 or 1 in the I2Cn_CTRL register.
- 2. For the minimum HFFPERCLK frequency required in Fast-mode Plus, refer to the I2C chapter in the reference manual.

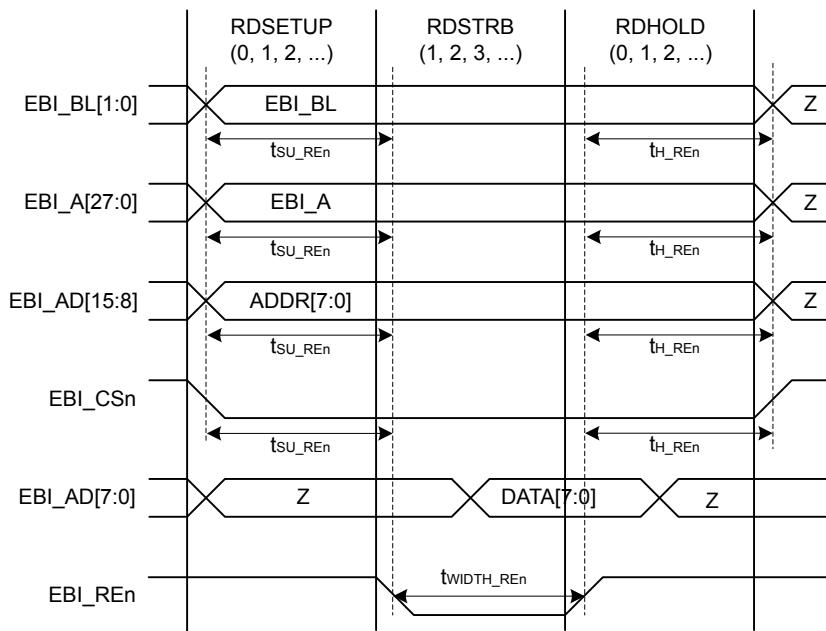


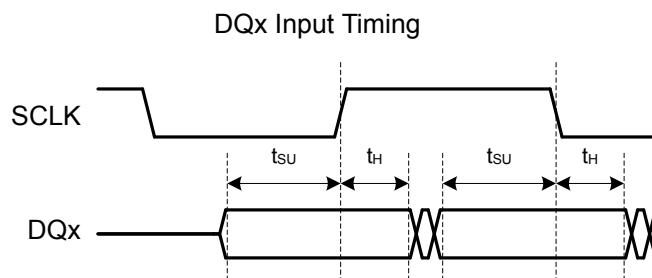
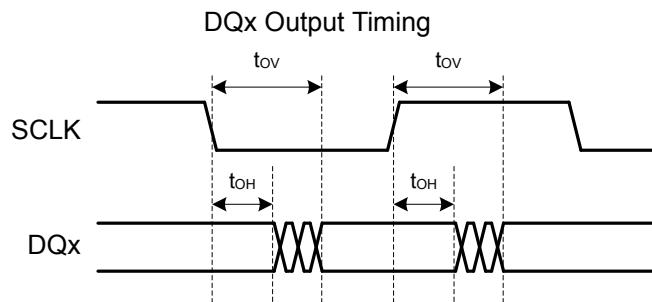
Figure 4.5. EBI Read Enable Output Timing Diagram

QSPI DDR Mode Timing (Locations 1, 2)

Timing is specified with voltage scaling disabled, PHY-mode, route locations other than 0, TX DLL = 53, RX DLL = 88, 20-25 pF loading per GPIO, and slew rate for all GPIO set to 6, DRIVESTRENGTH = STRONG.

Table 4.57. QSPI DDR Mode Timing (Locations 1, 2)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Half SCLK period	T/2	HFXO	(1/F _{SCLK}) * 0.4 - 0.4	—	—	ns
		HFRCO, AUXHFRCO, USHFRCO	(1/F _{SCLK}) * 0.44	—	—	ns
Output valid	t _{OV}		—	—	T/2 - 6.6	ns
Output hold	t _{OH}		T/2 - 52.2	—	—	ns
Input setup	t _{SU}		44.8	—	—	ns
Input hold	t _H		-2.4	—	—	ns

**Figure 4.22. QSPI DDR Timing Diagrams****QSPI DDR Flash Timing Example**

This example uses timing values for location 0 (DDR mode) to demonstrate the calculation of allowable flash timing using the QSPI in DDR mode.

- Using a configured SCLK frequency (F_{SCLK}) of 8 MHz from the HFXO clock source:
- The resulting minimum half-period, $T/2(\min) = (1/F_{SCLK}) * 0.4 - 0.4 = 49.6 \text{ ns}$.
- Flash will see a minimum setup time of $T/2 - t_{OV} = T/2 - (T/2 - 5.0) = 5.0 \text{ ns}$.
- Flash will see a minimum hold time of $t_{OH} = T/2 - 39.4 = 49.6 - 39.4 = 10.2 \text{ ns}$.
- Flash can have a maximum output valid time of $T/2 - t_{SU} = T/2 - 33.1 = 49.6 - 33.1 = 16.5 \text{ ns}$.
- Flash can have a minimum output hold time of $t_H = -0.9 \text{ ns}$.

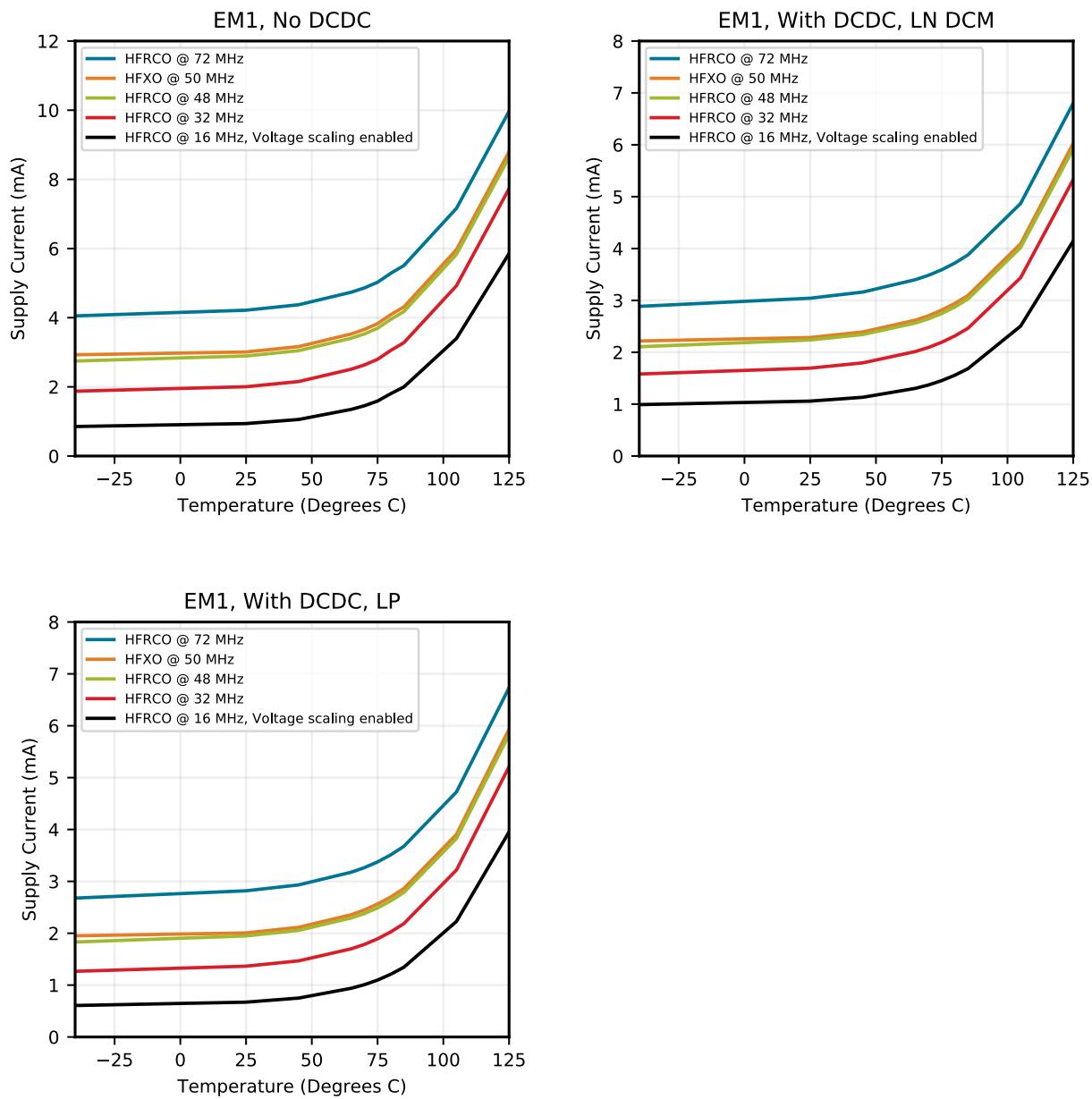


Figure 4.25. EM1 Sleep Mode Typical Supply Current vs. Temperature

Typical supply current for EM2, EM3 and EM4H using standard software libraries from Silicon Laboratories.

5.20 GPIO Functionality Table

A wide selection of alternate functionality is available for multiplexing to various pins. The following table shows the name of each GPIO pin, followed by the functionality available on that pin. Refer to [5.21 Alternate Functionality Overview](#) for a list of GPIO locations available for each function.

Table 5.20. GPIO Functionality Table

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PA15	BUSAY BUSBX LCD_SEG12	EBI_AD08 #0	TIM3_CC2 #0	ETH_MIIRXCLK #0 ETH_MDIO #3 US2_CLK #3	PRS_CH15 #0
PE15	BUSCY BUSDX LCD_SEG11	EBI_AD07 #0	TIM2_CDTI2 #2 TIM3_CC1 #0	ETH_RMIITXD0 #0 ETH_MIIRXD3 #0 SDIO_CMD #1 US0 RTS #0 QSPI0_DQS #1 LEU0_RX #2	PRS_CH14 #2 ETM_TD3 #4
PE14	BUSDY BUSCX LCD_SEG10	EBI_AD06 #0	TIM2_CDTI1 #2 TIM3_CC0 #0	ETH_RMIITXD1 #0 ETH_MIIRXD2 #0 SDIO_CLK #1 US0_CTS #0 QSPI0_SCLK #1 LEU0_TX #2	PRS_CH13 #2 ETM_TD2 #4
PE13	BUSCY BUSDX LCD_SEG9	EBI_AD05 #0	TIM1_CC3 #1 TIM2_CC2 #3 LE-TIM0_OUT1 #4	SDIO_CLK #0 ETH_MIIRXD1 #0 US0_TX #3 US0_CS #0 U1_RX #4 I2C0_SCL #6	LES_ALTEX7 PRS_CH2 #3 ACMP0_O #0 ETM_TD1 #4 GPIO_EM4WU5
PE12	BUSDY BUSCX LCD_SEG8	EBI_AD04 #0	TIM1_CC2 #1 TIM2_CC1 #3 WTIM0_CDTI2 #0 LETIM0_OUT0 #4	SDIO_CMD #0 ETH_MIIRXD0 #0 US0_RX #3 US0_CLK #0 U1_TX #4 I2C0_SDA #6	CMU_CLK1 #2 CMU_CLKI0 #6 LES_ALTEX6 PRS_CH1 #3 ETM_TD0 #4
PE11	BUSCY BUSDX LCD_SEG7	EBI_AD03 #0 EBI_CS3 #4	TIM1_CC1 #1 TIM4_CC2 #7 WTIM0_CDTI1 #0	SDIO_DAT0 #0 QSPI0_DQ7 #0 ETH_MIIRXDV #0 US0_RX #0	LES_ALTEX5 PRS_CH3 #2 ETM_TCLK #4
PE10	BUSDY BUSCX LCD_SEG6	EBI_AD02 #0 EBI_CS2 #4	TIM1_CC0 #1 TIM4_CC1 #7 WTIM0_CDTI0 #0	SDIO_DAT1 #0 QSPI0_DQ6 #0 ETH_MIIRXER #0 US0_TX #0	PRS_CH2 #2 GPIO_EM4WU9
PE9	BUSCY BUSDX LCD_SEG5	EBI_AD01 #0 EBI_CS1 #4	TIM4_CC0 #7 PCNT2_S1IN #1	SDIO_DAT2 #0 QSPI0_DQ5 #0 US5_RX #0	PRS_CH8 #2
PE8	BUSDY BUSCX LCD_SEG4	EBI_AD00 #0 EBI_CS0 #4	TIM2_CDTI0 #2 TIM4_CC2 #6 PCNT2_S0IN #1	SDIO_DAT3 #0 QSPI0_DQ4 #0 US5_TX #0 I2C2_SDA #0	PRS_CH3 #1
PI9		EBI_A14 #2	TIM1_CC3 #7 TIM4_CC1 #3	US4_CS #3	
PI6		EBI_A11 #2	TIM1_CC0 #7 TIM4_CC1 #2 WTIM3_CC0 #5	US4_TX #3	

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PD15		EBI_NANDREn #1	TIM2_CDTI2 #1 TIM3_CC0 #7 WTIM0_CDTI0 #1 PCNT1_S0IN #2	ETH_TSUEXTCLK #1 CAN0_TX #5 US5_CTS #1 I2C0_SCL #3	
PC13	VDAC0_OUT1ALT / OPA1_OUTALT #1 BUSACMP1Y BU-SACMP1X	EBI_ARDY #4	TIM0_CDTI0 #1 TIM1_CC0 #0 TIM1_CC2 #4 TIM5_CC2 #5 WTIM3_CC2 #2 PCNT0_S0IN #0 PCNT2_S1IN #4	US0_CTS #3 US1_RTS #4 US2_RTS #4 U0_CTS #3 U1_RX #0 I2C2_SCL #6	LES_CH13 PRS_CH21 #1 ACMP3_O #3
PC12	VDAC0_OUT1ALT / OPA1_OUTALT #0 BUSACMP1Y BU-SACMP1X		TIM1_CC3 #0 TIM5_CC1 #5 WTIM3_CC1 #2 PCNT2_S0IN #4	CAN1_RX #4 US0_RTS #3 US1_CTS #4 US2_CTS #4 U0_RTS #3 U1_TX #0 I2C2_SDA #6	CMU_CLK0 #1 LES_CH12 PRS_CH20 #1
PC11	BUSACMP1Y BU-SACMP1X	EBI_ALE #4 EBI_ALE #5 EBI_A23 #1	TIM5_CC0 #5 WTIM3_CC0 #2	CAN1_TX #4 US0_TX #2 I2C1_SDA #4	LES_CH11 PRS_CH19 #1
PA3	BUSAY BUSBX LCD_SEG16	EBI_AD12 #0 EBI_VSNC #3	TIM0_CDTI0 #0 TIM3_CC0 #5	ETH_RMIREFCLK #0 ETH_MII TXD1 #0 SDIO_DAT3 #1 US3_CS #0 U0_TX #2 QSPI0_DQ1 #1	CMU_CLK2 #1 CMU_CLK10 #1 CMU_CLK2 #4 LES_ALTEX2 PRS_CH9 #1 ETM_TD1 #3
PG2	BUSACMP2Y BU-SACMP2X	EBI_AD02 #2	TIM6_CC2 #0 TIM2_CDTI2 #3 WTIM0_CC0 #2 LETIM1_OUT0 #7	ETH_MII TXD2 #1 US3_CLK #4 QSPI0_DQ1 #2	CMU_CLK0 #3
PG1	BUSACMP2Y BU-SACMP2X	EBI_AD01 #2	TIM6_CC1 #0 TIM2_CDTI1 #3 WTIM0_CDTI2 #1 LETIM1_OUT1 #6	ETH_MII TXD3 #1 US3_RX #4 QSPI0_DQ0 #2	CMU_CLK1 #3
PC10	BUSACMP1Y BU-SACMP1X	EBI_A10 #2 EBI_A22 #1	TIM2_CC2 #2 TIM5_CC2 #4 WTIM3_CC2 #1	CAN1_TX #3 US0_RX #2	LES_CH10 PRS_CH18 #1
PC9	BUSACMP1Y BU-SACMP1X	EBI_A09 #2 EBI_A21 #1 EBI_A27 #3	TIM2_CC1 #2 TIM5_CC1 #4 WTIM3_CC1 #1	CAN1_RX #3 US0_CLK #2	LES_CH9 PRS_CH5 #0 GPIO_EM4_WU2
PC8	BUSACMP1Y BU-SACMP1X	EBI_A08 #2 EBI_A15 #0 EBI_A20 #1 EBI_A26 #3	TIM2_CC0 #2 TIM5_CC0 #4 WTIM3_CC0 #1	US0_CS #2	LES_CH8 PRS_CH4 #0
PA4	BUSBY BUSAX LCD_SEG17	EBI_AD13 #0 EBI_HSNC #3	TIM0_CDTI1 #0 TIM3_CC1 #5	ETH_RMIICRSDV #0 ETH_MII TXD0 #0 SDIO_DAT4 #1 US3_CTS #0 U0_RX #2 QSPI0_DQ2 #1	LES_ALTEX3 PRS_CH16 #0 ETM_TD2 #3
PG4	BUSACMP2Y BU-SACMP2X	EBI_AD04 #2	TIM6_CDTI1 #0 WTIM0_CC2 #2	ETH_MII TXD0 #1 US3_CTS #4 QSPI0_DQ3 #2	

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
BU_STAT	0: PE3		Backup Power Domain status, whether or not the system is in backup mode.
BU_VIN	0: PD8		Battery input for Backup Power Domain.
BU_VOUT	0: PE2		Power output for Backup Power Domain.
CAN0_RX	0: PC0 1: PF0 2: PD0 3: PB9	4: PG8 5: PD14 6: PE0 7: PI12	CAN0 RX.
CAN0_TX	0: PC1 1: PF2 2: PD1 3: PB10	4: PG9 5: PD15 6: PE1 7: PI13	CAN0 TX.
CAN1_RX	0: PC2 1: PF1 2: PD3 3: PC9	4: PC12 5: PA12 6: PG10 7: PI14	CAN1 RX.
CAN1_TX	0: PC3 1: PF3 2: PD4 3: PC10	4: PC11 5: PA13 6: PG11 7: PI15	CAN1 TX.
CMU_CLK0	0: PA2 1: PC12 2: PD7 3: PG2	4: PF2 5: PA12	Clock Management Unit, clock output number 0.
CMU_CLK1	0: PA1 1: PD8 2: PE12 3: PG1	4: PF3 5: PB11	Clock Management Unit, clock output number 1.
CMU_CLK2	0: PA0 1: PA3 2: PD6 3: PG0	4: PA3 5: PD10	Clock Management Unit, clock output number 2.
CMU_CLKIO	0: PD4 1: PA3 2: PB8 3: PB13	4: PE1 5: PD10 6: PE12 7: PB11	Clock Management Unit, clock input number 0.
DBG_SWCLKTCK	0: PF0		Debug-interface Serial Wire clock input and JTAG Test Clock. Note that this function is enabled to the pin out of reset, and has a built-in pull down.
DBG_SWDIOTMS	0: PF1		Debug-interface Serial Wire data input / output and JTAG Test Mode Select. Note that this function is enabled to the pin out of reset, and has a built-in pull up.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
TIM2_CC1	0: PA9 1: PA13 2: PC9 3: PE12	4: PC0 5: PC3 6: PG9 7: PG6	Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	0: PA10 1: PA14 2: PC10 3: PE13	4: PC1 5: PC4 6: PG10 7: PG7	Timer 2 Capture Compare input / output channel 2.
TIM2_CDTI0	0: PB0 1: PD13 2: PE8 3: PG0		Timer 2 Complimentary Dead Time Insertion channel 0.
TIM2_CDTI1	0: PB1 1: PD14 2: PE14 3: PG1		Timer 2 Complimentary Dead Time Insertion channel 1.
TIM2_CDTI2	0: PB2 1: PD15 2: PE15 3: PG2		Timer 2 Complimentary Dead Time Insertion channel 2.
TIM3_CC0	0: PE14 1: PE0 2: PE3 3: PE5	4: PA0 5: PA3 6: PA6 7: PD15	Timer 3 Capture Compare input / output channel 0.
TIM3_CC1	0: PE15 1: PE1 2: PE4 3: PE6	4: PA1 5: PA4 6: PD13 7: PB15	Timer 3 Capture Compare input / output channel 1.
TIM3_CC2	0: PA15 1: PE2 2: PE5 3: PE7	4: PA2 5: PA5 6: PD14 7: PB0	Timer 3 Capture Compare input / output channel 2.
TIM4_CC0	0: PF3 1: PF13 2: PF5 3: PI8	4: PF6 5: PF9 6: PD11 7: PE9	Timer 4 Capture Compare input / output channel 0.
TIM4_CC1	0: PF4 1: PF14 2: PI6 3: PI9	4: PF7 5: PD9 6: PD12 7: PE10	Timer 4 Capture Compare input / output channel 1.
TIM4_CC2	0: PF12 1: PF15 2: PI7 3: PI10	4: PF8 5: PD10 6: PE8 7: PE11	Timer 4 Capture Compare input / output channel 2.
TIM4_CDTI0	0: PD0		Timer 4 Complimentary Dead Time Insertion channel 0.
TIM4_CDTI1	0: PD1		Timer 4 Complimentary Dead Time Insertion channel 1.

Alternate Functionality	Location	Priority
US2_CLK	4: PF8 5: PF2	High Speed High Speed
US2_CS	4: PF9 5: PF5	High Speed High Speed
US2_RX	4: PF7 5: PF1	High Speed High Speed
US2_TX	4: PF6 5: PF0	High Speed High Speed

Table 5.28. ADC1 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSA Y	BUSA X	BUSADC1Y	BUSADC1X	Bus
PF15	PF15			PF14	PB14	PB15	PB15			CH31
PF14	PF13	PF13		PF12	PB12	PB13	PB13	PB14		CH30
PF12	PF11	PF11		PF10	PB10	PB11	PB11			CH29
PF10	PF9	PF9		PF8	PB9	PB9	PB9	PB10		CH28
PF8	PF7	PF7		PF6	PB6	PB6	PB6	PB6		CH27
PF6	PF5	PF5		PF4	PB4	PB5	PB5	PB4		CH26
PF4	PF3	PF3		PF2	PB2	PB3	PB3	PB2		CH25
PF2	PF1	PF1		PF0	PB0	PB1	PB1	PB0		CH24
PF0	PE15	PE15		PE14	PA14	PA15	PA15	PA14		CH23
PE14	PE13	PE13		PE12	PA12	PA13	PA13	PA12		CH22
PE12	PE11	PE11		PE10	PA10	PA11	PA11	PA10		CH21
PE10	PE9	PE9		PE8	PA8	PA9	PA9	PA8		CH20
PE8	PE7	PE7		PE6	PA6	PA7	PA7	PA6		CH19
PE6	PE5	PE5		PE4	PA4	PA5	PA5	PA4		CH18
PE4					PA3	PA3	PA3	PA2		CH17
	PE1	PE1			PA1	PA1	PA1	PA0		CH16
PE0			PE0	PE0	PA0	PA0	PA0	PA0		CH15

7.2 BGA152 PCB Land Pattern

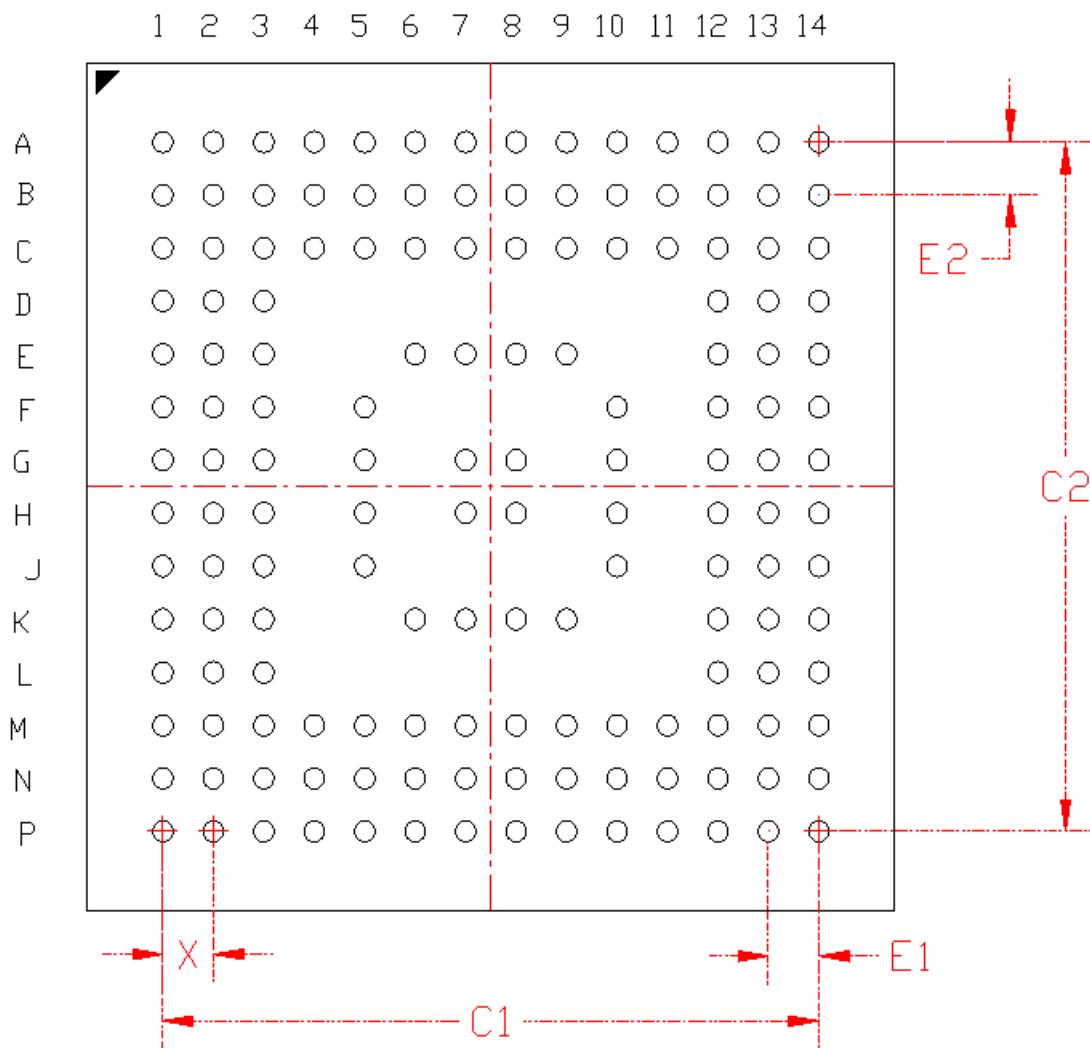


Figure 7.2. BGA152 PCB Land Pattern Drawing

Table 11.1. TQFP64 Package Dimensions

Dimension	Min	Typ	Max
A	—	1.15	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	—	0.20
c1	0.09	—	0.16
D	12.00 BSC		
D1	10.00 BSC		
e	0.50 BSC		
E	12.00 BSC		
E1	10.00 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
R1	0.08	—	—
R2	0.08	—	0.20
S	0.20	—	—
θ	0	3.5	7
Θ1	0	—	0.10
Θ2	11	12	13
Θ3	11	12	13
Note:			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			
3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.			

13. Revision History

Revision 0.6

March, 2018

- Removed "Confidential" watermark.
- Updated [4.1 Electrical Characteristics](#) and [4.2 Typical Performance Curves](#) with latest characterization data.

Revision 0.2

October, 2017

- Updated memory maps to latest formatting and to include all peripherals.
- Updated all electrical specifications tables with latest characterization results.
- **Absolute Maximum Ratings Table:**
 - Removed redundant I_{VSSMAX} line.
 - Added footnote to clarify V_{DIGPIN} specification for 5V tolerant GPIO.
- **General Operating Conditions Table:**
 - Removed dV_{DD} specification and redundant footnote about shorting VREGVDD and AVDD together.
 - Added footnote about IOVDD voltage restriction when CSEN peripheral is used with chopping enabled.
- **Flash Memory Characteristics Table:** Added timing measurement clarification for Device Erase and Mass Erase.
- **Analog to Digital Converter (ADC) Table:**
 - Added header text for general specification conditions.
 - Added footnote for clarification of input voltage limits.
- Minor typographical corrections, including capitalization, mis-spellings and punctuation marks, throughout document.
- Minor formatting and styling updates, including table formats, TOC location, and boilerplate information throughout document.

Revision 0.1

April 27th, 2017

Initial release.